

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) ~~Method~~ A method for manufacturing smart cards, each having an antenna with ends or connection pads for connection to an electronic module, comprising the following steps:

producing the antenna with at least two turns, on a support sheet, such that said turns are located outside the connection pads and encircle said connection pads, and connecting at least one of the ends of the antenna to a respective one of said connection pads by means of an insulating bridge disposed on a surface of said turns that is away from said support sheet.

2. (Previously Presented) A method according to Claim 1, wherein the insulating bridge is produced by covering the turns of the antenna with an insulating layer in one zone and depositing on this insulating layer a conductive element so that one outer end of the antenna can be connected to one connection pad.

3. (Canceled)

4. (Previously Presented) A method according to claim 1, further comprising the following steps:

assembling the support sheet to plastic foils to form a card body,

machining a cavity and connection recesses in an upper face of the card body, so that the machined plane of the cavity is situated below the plane of the connection pads of the antenna, and the connection recesses are situated above the connection pads of the antenna in order to expose said pads, and

fixing an electronic module into the cavity, the module having on its lower side, facing towards the inside of the cavity, conductive pads in electrical contact with the connection pads of the antenna by means of a conductive linking element located in the connection recesses.

5. (Canceled)

6. (Previously Presented) A method according to claim 4, wherein the support sheet is located between the plastic foils so as to form the neutral axis of the card.

7. (Previously Presented) A method according to claim 1, wherein the antenna is produced by incrustation on the support sheet.

8. (Previously Presented) A method according to claim 1, wherein the connection pads are produced in a zigzag pattern.

9. (Previously Presented) A method according to claim 4, wherein the machining of the connection recesses is carried out through the connection pads of the antenna.

10. (Previously Presented) A method according to claim 4, wherein the connection recesses are diametrically opposite each other and are situated on a mid-perpendicular of the cavity.

11. (Previously Presented) A method according to claim 4, wherein the connection recesses are situated side-by-side and on either side of a mid-perpendicular of the cavity.

12. (Previously Presented) A method according to claim 1, wherein the electronic module comprises an integrated circuit microchip and a single-sided printed circuit having flush contact zones defined by an ISO standard, and wherein said pads are located outside the contact zones defined by the ISO standard,

13. (Previously Presented) A method according to claim 4, wherein the electronic module comprises an integrated circuit microchip and a double-sided printed circuit without conductive paths between its two faces, the double-sided circuit comprising an insulating foil having on one face a first set of conductive pads that form access contacts for the smart card, and on the other face a second set of conductive pads that are connected to the antenna, and wherein said connection pads comprise contact zones located on the same side of the cavity and on either side of a mid-perpendicular of this cavity, or on a mid-perpendicular of the cavity on two opposite sides, each said contact zone being extended by a track with its edge parallel to the electronic module.

14. (Previously Presented) A method according to claim 1, wherein the connection between the connection pads of the antenna and the module is formed by a solder with a low melting point.

15. (Previously Presented) A method according to Claim 14, wherein the solder comprises an alloy with a basis of indium and tin

16. (Previously Presented) A method according to claim 14, wherein the solder comprises not more than 52% by weight of indium and 48% by weight of tin.

17. (Previously Presented) A method according to Claim 14, wherein the solder comprises an alloy with a basis of bismuth, tin and lead.

18. (Previously Presented) A method according to Claim 17, wherein the solder comprises not more than 46% by weight of bismuth, 34% by weight of tin and 20% by weight of lead.

19. (Previously Presented) A method according to Claim 14, wherein the solder comprises an alloy with a basis of bismuth, tin and indium.

20. (Previously Presented) A method according to Claim 19, wherein the solder comprises not more than 57% by weight of bismuth, 26% by weight of indium and 17% by weight of tin,

21. (Previously Presented) A method according to claim 1, wherein the connection between the connection pads of the antenna and of the module is formed by means of a grease charged with metallic particles.

22. (Previously Presented) A method according to claim 1, wherein the connection between the connection pads of the antenna and the module is formed by means of a silicon gasket charged with metallic particles.

23. (Previously Presented) A method according to claim 1, further including the step of depositing balls of gold by thermo compression on the module in order to increase the bonding surface between the module and the antenna.

24. (Previously Presented) A method according to claim 2, further comprising the following steps:

assembling the support sheet to plastic foils to form a card body;

machining cavity and connection recesses in an upper face of the card body, so that the machined plane of the cavity is situated below the plane of the connection

pads of the antenna, and the connection recesses are situated above the connection pads of the antenna in order to expose said pads; and

fixing an electronic module into the cavity, the module having on its lower side, facing towards the inside of the cavity, conductive pads in electrical contact with the connection pads of the antenna by means of a conductive linking element located in the connection recesses.

25. (Canceled)

26. (Canceled)

27. (Previously Presented) Manufacturing method according to claim 20, wherein the connection between the connection pads of the antenna and the conductive pads of the module (M) is formed by means of a grease charged with metallic particles.

28. (Canceled)

29. (Previously Presented) Manufacturing method according to claim 20, wherein the connection between the connection pads of the antenna and the conductive pads of the module (M) is formed by means of a silicon gasket charged with metallic particles.

30. (Canceled)

31. (Previously Presented) A support sheet, comprising:

an antenna winding with at least two turns, a pair of connection pads both disposed on a common side of said antenna winding, an insulating material covering a zone across said antenna winding, and a conductive element on said insulating material that connects an end of said winding on a side opposite said common side to one of said connection pads.

32. (Previously Presented) A smart card including the support sheet of claim 31.

33. (Previously Presented) A smart card including the support sheet of claim 31 and an integrated circuit chip connected to said connection pads.

34. (Previously Presented) A support sheet, comprising:

an antenna winding with at least two turns and a pair of ends that are respectfully associated with two connection points, said antenna being incrustated on said sheet and including a link that crosses said turns to connect the outside turn to one of said connection points, with said link being insulated from said turns to avoid a short circuit.

35. (Previously Presented) The support sheet of claim 34 wherein said antenna is incrustated on said support sheet by means of an ultrasound technique.

36. (Previously Presented) A smart card including the support sheet of claim 34.

37. (Previously Presented) A smart card including the support sheet of claim 34 and an integrated circuit chip connected to said connection pads.

38. (Previously Presented) A method for manufacturing smart cards, comprising the following steps:

providing a support sheet having an antenna with a plurality of turns, a pair of connection pads disposed on a common side of said turns, and a link crossing said turns that connects the opposite side of said turns to one of said connection pads;

laminating said support sheet between a pair of plastic sheets;

machining a cavity in one of said plastic sheets subsequent to said laminating step to expose said connection pads; and

placing an integrated circuit chip within said cavity so as to be in electrical contact with said connection pads.

39. (Previously Presented) The method of claim 38 wherein said integrated circuit chip is disposed within a module having conductors on one side for connecting said chip to said connection pads, and conductors on the opposite side that provide access to the smart card.